

## PRODUCT/PROCESS CHANGE NOTIFICATION

PCN APM-DIS/07/2725 Notification Date 07/16/2007

# APM - ASD & IPAD Division DVIULC6-4SC6 & HDMIULC6-4SC6 in SOT23-6L package Implementation of secondary passivation DIS - ASD & IPAD

#### **Table 1. Change Identification**

Product Identification (Product Family/Commercial Product)	DVIULC6-4SC6 & HDMIULC6-4SC6 in SOT23-6L package
Type of change	Product design change
Reason for change	Production rationalization
Description of the change	A PSG passivation layer is implemented above the primary passivation in SiO2. This change has no impact on the electrical parameters, including the leakage current and capacitance parameters. This was verified in the qualification program through product characterizations.
Product Line(s) and/or Part Number(s)	See attached
Description of the Qualification Plan	See attached
Change Product Identification	Date code, internal codification & QA number
Manufacturing Location(s)	

#### **Table 2. Change Implementation Schedule**

Forecasted implementation date for change	10-Aug-2007
Forecasted availabillity date of samples for customer	09-Jul-2007
Forecasted date for <b>STMicroelectronics</b> change Qualification Plan results availability	09-Jul-2007
Estimated date of changed product first shipment	15-Oct-2007

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Table 3. List of Attachments								
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Customer Part numbers list	
Qualification Plan results	

Customer Acknowledgement of Receipt	PCN APM-DIS/07/2725
Please sign and return to STMicroelectronics Sales Office	Notification Date 07/16/2007
□ Qualification Plan Denied	Name:
□ Qualification Plan Approved	Title:
	Company:
☐ Change Denied	Date:
□ Change Approved	Signature:
Remark	

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#### **DOCUMENT APPROVAL**

Name	Function
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PCN APM-DIS/07/2725

## APM - ASD & IPAD Division<sup>1</sup> <u>DVIULC6-4SC6 & HDMIULC6-4SC6 in SOT23-6L package</u>:

Implementation of secondary passivation



July 2007 5

#### WHY THIS CHANGE?

STMicroelectronics has decided the implementation of a **secondary passivation** on its **DVIULC6-4SC6** & **HDMIULC6-4SC6** in SOT23-6L package to **rationalize** its production. At the same time, the **bonding pad** will be slightly resized for the same reason.

#### **WHAT IS THE CHANGE?**

While the diffusion steps for the elaboration of the devices remain exactly the same, a PSG\* passivation layer is implemented above the primary passivation in SiO<sub>2</sub>. This change has no impact on the electrical parameters, including the leakage current and capacitance parameters. This was verified in the qualification program through product characterizations.

(\*) Phosphosilicate glass

#### **HOW AND WHEN?**

#### Qualification and test results:

The **reliability tests plan** supporting the change is provided in **appendix 1** of the present document. The production ramp-up will be monitored with a **pre-launch control plan** implemented on selected parameters.

The **qualification report** is available on request from **now**.

#### Sampling:

Qualification samples of the devices produced with secondary passivation are available now.

#### Change implementation schedule:

The **production start** and **first shipments** will be implemented according to our work in progress and materials availability as indicated in the schedule below:

Salestypes	Production Start	1st Shipments
ALL	From Week 32-2007	From Week 42-2007

Lack of acknowledgement of the PCN within **30 days** will constitute acceptance of the change. After acknowledgement, lack of additional response within the **90 day** period will constitute acceptance of the change (Jedec Standard No. 46-C). In any case, **first shipments** may start earlier with customer's **written agreement**.

#### Marking and Traceability:

Parts with the secondary passivation will have the same marking as currently produced parts. The **traceability** will be ensured by the **date code**, by an **internal codification**, and by the **Q.A. number**.

Appendix 1: Reliability tests for qualification program of change

#### <u>DVIULC6-4SC6 & HDMIULC6-4SC6 in SOT23-6L package</u>: Implementation of secondary passivation <u>Reliability tests plan for QUALIFICATION PROGRAM</u> (according to AEC Q101 standard)

Product Family	Test Vehicle Salestypes		
Low capacitance	DVIULC-4SC6		
Protection Devices	HDMIULC6-4SC6		

QUALIFICATION TESTS					
TEST	CONDITIONS	DURATION	NBR OF LOTS (*)	SAMPLE SIZE	ACCEPTANCE CRITERIA
Parametric verification	Data sheet specification	Not applicable	3	30 pcs / lot	Datasheet
Pressure Cooker Test JESD22-A102	121°C 2 atm 100%RH	96 Hours	3	77 pcs / lot	0 failure
Temperature Cycling JESD22 A104	-55°C/+150°C - Air/Air	1000 cycles	3	77 pcs / lot	0 failure
Temperature Humidity Bias JESD22 A101	Tamb = 85°C RH = 85% V = VRM	1000 hours	3	77 pcs / lot	0 failure
High Temperature Reverse Bias JESD22-A108	V = VRM $Tj = 150$ °C	1000 hours	3	77 pcs / lot	0 failure
Construction analysis	Random samples	Not applicable	1	5pcs	Assembly rules
Resistance to Solder Heat Jedec JESD22-B106-B	2 oil dipping at 260°C	10s on / 15 s off	3	30 pcs / lot min	0 failure

<sup>(\*)</sup> Lots selected among test vehicles indicated above or of other devices presenting sufficient technological similarities. NOTE: A preconditioning sequence is performed before PCT, TC and THB reliability tests according to JESD22-A113.

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